

ADQ32 Datasheet



The ADQ32 is a high-end 12-bit dual-channel data acquisition board optimized for use in high-throughput scientific applications. The ADQ32 features:

- One and Two analog input channels
- 5 and 2.5 GSPS per channel
- 7 GByte/s sustained data transfer rate to GPU
- 7 GByte/s sustained data transfer rate to CPU
- Two external triggers
- General Purpose Input/Output (GPIO)
- Open FPGA for real-time signal processing



1 ADQ32 INTRODUCTION

1.1 Features

- One and two analog input channels
- 5 and 2.5 GSPS sampling rate per channel
- 12 bits vertical resolution
- DC-coupled with 1 GHz bandwidth
- Programmable DC-offset
- Internal and external clock reference
- Internal and external sampling clock
- Clock reference output
- Internal and external triggers
- 8 GBytes data memory
- 7 GByte/s sustained data streaming to CPU and GPU
- 7 GByte/s peer-to-peer data streaming to GPU
- Data interface PCIe Gen3 x8

1.2 Applications

- Swept-Source Optical Coherence Tomography (SS-OCT)
- Time-of-flight Mass Spectrometry
- Distributed Optical Fiber Sensing
- LIDAR

1.3 Advantages

- A compact high-performance digitizer that optimize the system solution
- Real-time processing and high data throughput
- Teledyne SP Devices' design services are available for fast integration to reduce time-tomarket

1.4 System design optimization; open FPGA and streaming to CPU and GPU

High-performance data acquisition systems require high speed real-time analysis. ADQ32 offers a variety of options for efficient system design:

Streaming to GPU

ADQ32 supports up to 7 GByte/s peer-to-peer streaming and streaming via pinned buffer to GPU. A GPU offers a powerful platform for implementing application-specific signal processing algorithms.

Streaming to CPU

ADQ32 supports up to 7 GByte/s to host PC. Implementing the application-specific algorithms in the CPU results in an efficient system.

Open FPGA for real-time processing

ADQ32 offers an open FPGA for implementation of the application-specific computations in the FPGA. This gives the most compact system design. Firmware development kit is ordered separately.



2 TECHNICAL DATA

Technical parameters are valid for ADQ32 operating with firmware FWDAQ. All parameters are typical unless otherwise noted.

Table 1 Analog input (front panel label A and B)

Parameter	Condition	Unit	Min	Typical	Max
Basic parameters					
Number of channels	2 channels mode			2	
Sampling rate per channel	2 channels mode	Gsample/s		2.5	
Number of channels	1 channel mode			1	
Sampling rate	1 channel mode	Gsample/s		5	
Bandwidth	-3dB	GHz		1	
Input range		Vpp		0.5	
Input impedance		Ω		50	
Coupling				DC	
Connector type				SMA	
Programmable DC-offset					
DC-offset range		V	-0.25		+0.25
AC performance 2 channels m	ode				
Cross talk	< 1 GHz	dBFS		-70	
Noise power density	0 to 1.25 GHz	dBFS/√Hz		-148	
SNR	260 MHz, -1dBFS	dBc		55	
SFDR	260 MHz, -1dBFS	dBc		66	
ENOB relative full scale	10 MHz, -1dBFS	bits		9	
ENOB relative full scale	260 MHz, -1dBFS	bits		8.9	
ENOB relative full scale	810 MHz, -1dBFS	bits		8.5	
AC performance, 1 channels n	node, no FIR filter				
SNR	260 MHz, -1dBFS	dBc		54	
SFDR	260 MHz, -1dBFS	dBc		65	
ENOB relative full scale	10 MHz, -1dBFS	bits		8.9	
ENOB relative full scale	260 MHz, -1dBFS	bits		8.8	
ENOB relative full scale	810 MHz, -1dBFS	bits		8.5	
AC performance, 1 channels n	node, FIR filter ¹				
SNR	260 MHz, -1dBFS	dBc		57	
ENOB relative full scale	10 MHz, -1dBFS	bits		9.2	
ENOB relative full scale	260 MHz, -1dBFS	bits		9.2	
ENOB relative full scale	810 MHz, -1dBFS	bits		9.1	

 $^{^1}$ Built-in user-programmable digital FIR filter; symmetrical, 17 taps. Filter coefficients used for this test are [57, 92, -279, 21, 704, -720, -1163, 4127, 10784] / 2^{14} .



Table 2 Clock generator and front panel CLK connector.

Parameter	Condition	Unit	Min	Typical	Max
Internal clock reference					
Frequency		MHz		10	
Accuracy		ppm		±3	
				±1/year	
Internal sampling clock gen	erator ²				
Frequency range 1	2 channels	MHz	2440	2500	2500
Frequency range 2	2 channels	MHz	1840		1970
Frequency range 1	1 channel	MHz	4880	5000	5000
Frequency range 2	1 channel	MHz	3680		3940
External clock reference inp	out (from front pane	CLK connec	tor) ³		
Frequency		MHz	1	10	500
Frequency ⁴	Jitter cleaner	MHz	10	10	500
	enabled		-10 ppm		+10 ppm
Frequency	Delay line used	MHz		10	100
Delay line tuning range		ps		500	
Signal level		Vpp	0.5		3.3
Input impedance	AC	Ω		50	
Input impedance	DC	Ω		10k	
Input impedance (high) 5	AC	Ω		200	
Clock reference output (on	front panel CLK con	nector) ⁶			
Frequency		MHz		10	
Signal level	Into 50-Ω load	Vpp		1.2	
Output impedance	AC	Ω		50	
Output impedance	DC	Ω		10k	
External direct sampling clo	ck input (from front	panel CLK c	onnector) ⁷		
Frequency ⁸		MHz	1000	2500	2500
Signal level		Vpp	0.5		3.3
Impedance	AC	Ω		50	
Impedance	DC	Ω		10k	
Physical connector label CLI	(
Connector type				SMA	

² The internal clock generator can generate frequencies in 2 different ranges.

³ Using a clock reference from an external source to synchronize the ADQ32 to the external source.

⁴ The jitter cleaner requires the reference frequency to be a multiple of 10 MHz within ± 10ppm.

⁵ Software-selectable high-impedance mode.

⁶ The internal clock reference of the ADQ32 is made available to synchronize external equipment.

⁷ Using an external clock while bypassing the internal clock generator.

 $^{^{\}rm 8}$ In one channel mode, the sampling frequency is 2 time the external clock frequency.



Table 3 Front panel TRIG connector

Parameter	Condition	Unit	Min	Typical	Max
Connector				SMA	
Used as input (trigger in or GI	PIO)				
Impedance	DC	Ω		50	
Impedance (high) 9	DC	Ω		500	
Signal level	50-Ω mode	V	-0.5		3.3
Adjustable threshold	50-Ω mode	V	0		2.8
Signal level	High impedance	V	-0.5		5.5
Adjustable threshold	High impedance	V	0		2.3
Pulse repetition frequency	As trigger	MHz			10
Time resolution 10	As trigger	ps		50	
Update rate ¹⁰	As GPIO	MHz			156.25
Used as output (trigger out or	GPIO)				
Impedance	DC	Ω		50	
Output level high VOH	Into 50-Ω load	V	1.8		
Output level low VOL	Into 50-Ω load	V			0.1
Pulse repetition frequency		MHz			156.25

Table 4 Front panel SYNC connector (sync is a trigger signal with limited timing resolution)

Parameter	Condition	Unit	Min	Typical	Max
Connector				SMA	
Used as input (sync in or GPIC	0)				
Impedance	DC	Ω		50	
Impedance (high) 9	DC	Ω		500	
Signal range	50-Ω mode	V	-0.5		3.3
Adjustable threshold	50-Ω mode	V	0		2.8
Signal level	High impedance	V	-0.5		5.5
Adjustable threshold	High impedance	V	0		2.3
Pulse repetition frequency	As trigger	MHz			10
Time resolution 10	As trigger	ns		3.2	
Update rate ¹⁰	As GPIO	MHz			156.25
Used as output (sync out or G	PIO)				
Impedance	DC	Ω		50	
Output level high VOH	Into 50-Ω load	V	1.8		
Output level low VOL	Into 50-Ω load	V			0.1
Pulse repetition frequency		MHz			156.25

⁹ Software-selectable high-impedance mode.

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 $^{^{10}}$ Timing properties are valid for 2.5 GSPS in 2 channel mode and 5 GSPS in 1 channel mode. Timing properties scale linearly with sampling frequency.



Table 5 Front panel GPIO connector

Parameter	Condition	Unit	Min	Typical	Max
Connector type				SMA	
Used as input					
Impedance		Ω		50	
Impedance (high) 9		kΩ		10	
Input level high VIH		V	2		
Input level low VIL		V			0.8
Update rate 10		MHz			156.25
Used as output	·				
Output Impedance		Ω		50	
Output level high VOH	Into 50-Ω load	V	1.5		
Output level high VOH	No load	V	3.2		
Output level low VOL	Into 50-Ω load	V			0.1
Output level low VOL	No load	V			0.1
Update rate 10		MHz			156.25

Table 6 Environment and mechanical parameters

Parameter	Condition	Unit	Min	Typical	Max
Power and temperature					
Power consumption 11 12	FWDAQ	W		30	
Power supply		V	10.8	12	13.2
Operating temperature	At fan inlet	°C	0		45
Size					
Width				1 slot	
Length		mm		225.7	
Height		mm		111.2	
Compliances					
RoHS3				Yes	
CE				Yes	
FCC	Exclusion according to CFR 47, part 15, paragraph 15.103(c)				

¹¹ Power consumption depends on firmware option and use case.

¹² Power consumption is measured during acquisition and streaming of data at 5 Gbyte/s to PC.



Table 7 Data acquisition

Parameter	Condition	Unit	Min	Typical	Max
Re-arm time		ns			20
Acquisition memory (Data FIFO)	Shared by all channels	GBytes		8	
Record length		samples	16		2 ³¹
Pre-trigger ¹³		samples	0		16 360
Length granularity, pre-trigger		samples	8		
Trigger delay ¹⁴		samples	0		2 ³² -8
Length granularity, trigger delay		samples	8		

Table 8 Data transfer

Parameter	Unit	Value
Supported versions of data transfer standard PCIe		Gen1
		Gen2
		Gen3
Supported number of lanes		1
		4
		8
Data rate to CPU sustained with headers	GByte/s	5
Data rate to CPU sustained without headers	GByte/s	7
Data rate to GPU sustained without headers	GByte/s	7
Data rate peer-to-peer to GPU sustained without headers	GByte/s	7

Table 9 Software support

Parameter	Value
Operating system	Windows 10
	Linux
GUI	Digitizer Studio
Example code	C, Python
API	C / C++

 $^{^{\}rm 13}$ Pre-trigger is set by assigning the parameter "horizontal offset" a negative value

¹⁴ Trigger delay is set by assigning the parameter "horizontal offset" a positive value



3 FEATURES FOR DATA FLOW CONTROL, SYNCHRONIZATION AND PROCESSING

The ADQ32 features an advanced machine for flow control, synchronization and signal processing. The block diagrams are shown in Figure 1 and Figure 2. The features are described in the following tables.

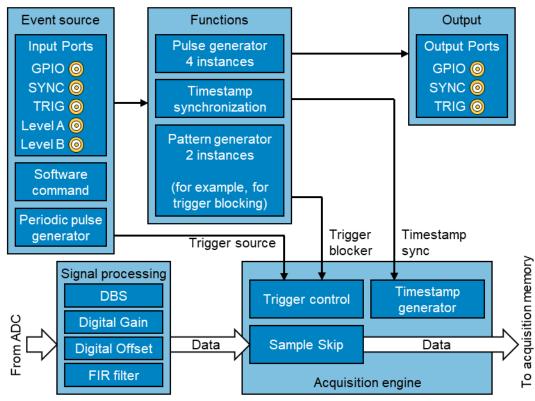


Figure 1 Flow control and synchronization block diagram.

Table 10 Digital signal processing blocks

Object type	Available selections
Digital Signal Processing	Digital Baseline Stabilizer (DBS)
Included signal processing in the data	Digital gain
path for enhanced signal quality.	Digital offset
	Digital FIR filter



Table 11 Flow control blocks

Object type	Available selections
Input ports	Front panel TRIG
Electrical connections to the ADQ32 for	Front panel SYNC
real-time operation (excluding the PCIe	Front panel GPIO
data interface) Used as event source.	Front panel CLK (clock reference or clock input only)
	Analog channel A
	Analog channel B
Event sources	Software command
Signals for real-time control of activities	External TRIG
in the firmware of ADQ32.	External SYNC
	External GPIO
	Internal periodic event generator
	Level analog channel A
	Level analog channel B
Functions	Pattern generator for timestamp synchronization
Included operations for real-time control	Pattern generator general purpose, 2 instances
of activities in the firmware of ADQ32.	Pulse generator, 4 instances
Output ports	Front panel TRIG
Electrical connections to the ADQ32 for	Front panel SYNC
real-time operation (excluding the PCle	Front panel GPIO
data interface).	Front panel CLK (clock reference output only)

Table 12 Firmware functions for flow control

Function	Modes/selections	Event sources as stimuli
Pattern generator for		Software command
timestamp sync		External TRIG
Control the time of		External SYNC
the ADQ32.		Internal periodic event generator
Pulse generator	Rising edge	Software command
Control output pulse	Falling edge	External TRIG
shapes. Three	Pulse length	External SYNC
instances.	Polarity	Internal periodic event generator
Pattern generator	Once	Software command
general purpose	Window	External TRIG
For example, used for	Gate	External SYNC
trigger blocking.	Trigger counter	Internal periodic event generator



Table 13 Firmware functions for acquisition

Function	Modes	Event Sources as stimuli
Trigger		Software command
Initiate the acquisition		External TRIG
of a data record.		External SYNC
		Internal periodic event generator
		Level analog channel A
		Level analog channel B
Data acquisition	Streaming with header	
modes	Streaming without header	
Configurations for		
sending digital data to		
the host PC.		

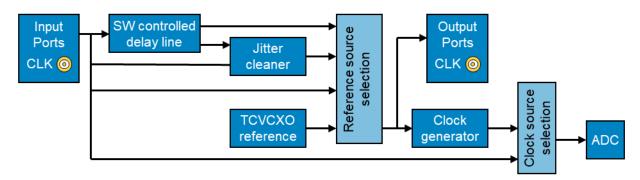


Figure 2 Clock generation block diagram.

Table 14 Clock generation

Function	Modes		
Clock reference source	Internal		
Phase and frequency reference for the	External		
clock system.	External with jitter cleaner and/or delay line		
Sampling clock sources	Internal clock generator		
Actual clock for taking the samples of the	Direct external clock		
analog data.			
Clock output	Selected clock reference		

4 CHANGING NUMBER OF CHANNEL

Changing from 2 channels to 1 channel is done by changing firmware image in the FPGA. Both firmware images are available on the ADQ32 digitizer. Use the software tool ADQAssist to change boot image. Changing firmware requires power cycle PC for the PCIe to enumerate.



5 ABSLOUTE MAXIMUM RATINGS

Table 15 Absolute maximum ratings

Parameter	Condition	Unit	Min	Max
Power supply to GND		V	-0.4	14
Operating temperature		°C	0	45
Analog in to GND		V	-1.75	+1.75
TRIG to GND	50-Ω mode	V	-2	5
SYNC to GND	50-Ω mode	V	-2	5
TRIG to GND	500-Ω mode	V	-2	6
SYNC to GND	500-Ω mode	V	-2	6
CLK REF to GND AC amplitude		Vpp		5
CLK REF to GND DC-level		V	-5	5
GPIO to GND		V	-1.5	5

Exposure to conditions exceeding these ratings may reduce lifetime or permanently damage the device. The digitizer with PCIe format has a built-in fan to cool the device. The built-in temperature monitoring unit will protect the digitizer from overheating by temporarily shutting down parts of the device in an overheat situation.

The SMA connectors have an expected lifetime of 500 operations. For frequent connecting and disconnecting of cables, connector savers are recommended.



6 TYPICAL PERFORMANCE

6.1 Frequency response

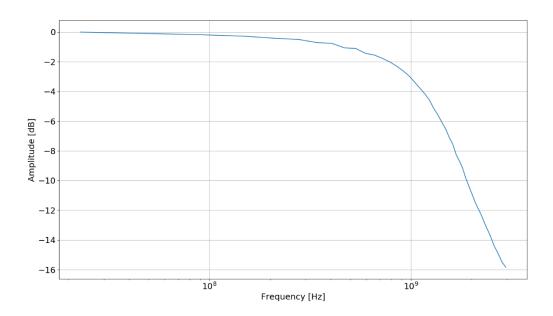


Figure 3 Frequency response, typical performance.

6.2 FFT

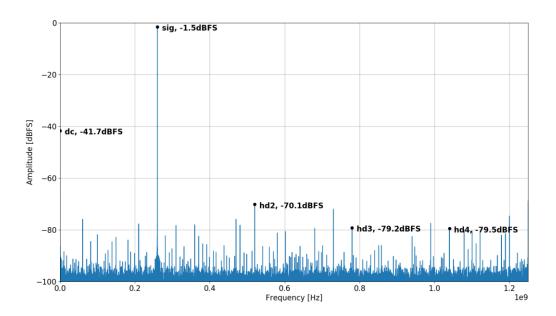


Figure 4 FFT typical performance 2.5 GSPS.



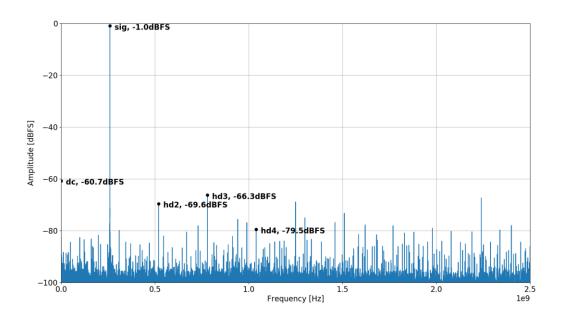


Figure 5 FFT typical performance at 5 GSPS

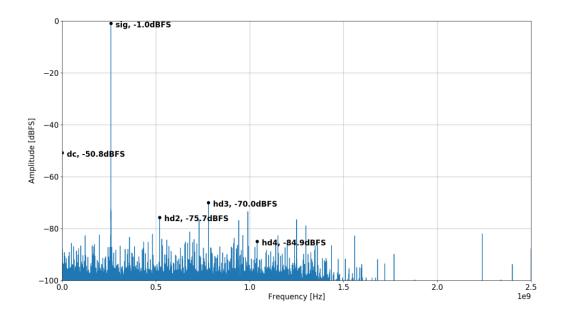


Figure 6 FFT typical performance 5 GSPS, using digital FIR filter.



7 BLOCK DIAGRAM

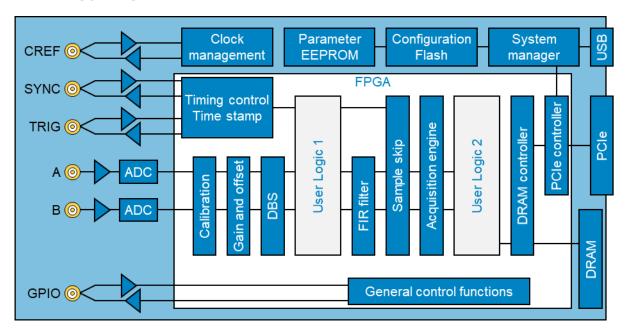


Figure 7 Block diagram.

Figure 7 shows a block diagram of the ADQ32. The boxes "User Logic" are open for custom real-signal processing thought the firmware development kit (purchased separately).

8 HOST PC INTERFACE PCIE

The ADQ32-PCIe is powered from the power supply of the PC via a PCI Express 6-pin (2x3) auxiliary power supply connector. The connection in the cable should be as in Figure 8. A suitable connector is for example Molex 45559-0002.

It is important that the auxiliary power supply is turned on immediately when the PC starts. Otherwise, the digitizer will not be recognized on the PCI Express bus.

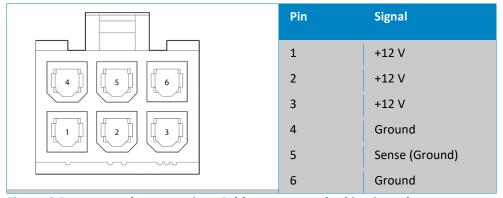


Figure 8 Power supply connection. Cable connector, looking into the connector end.



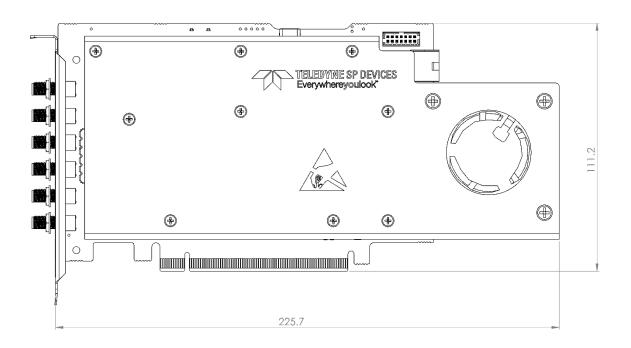


Figure 9 Mechanical drawing



Figure 10 ADQ32 photo



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